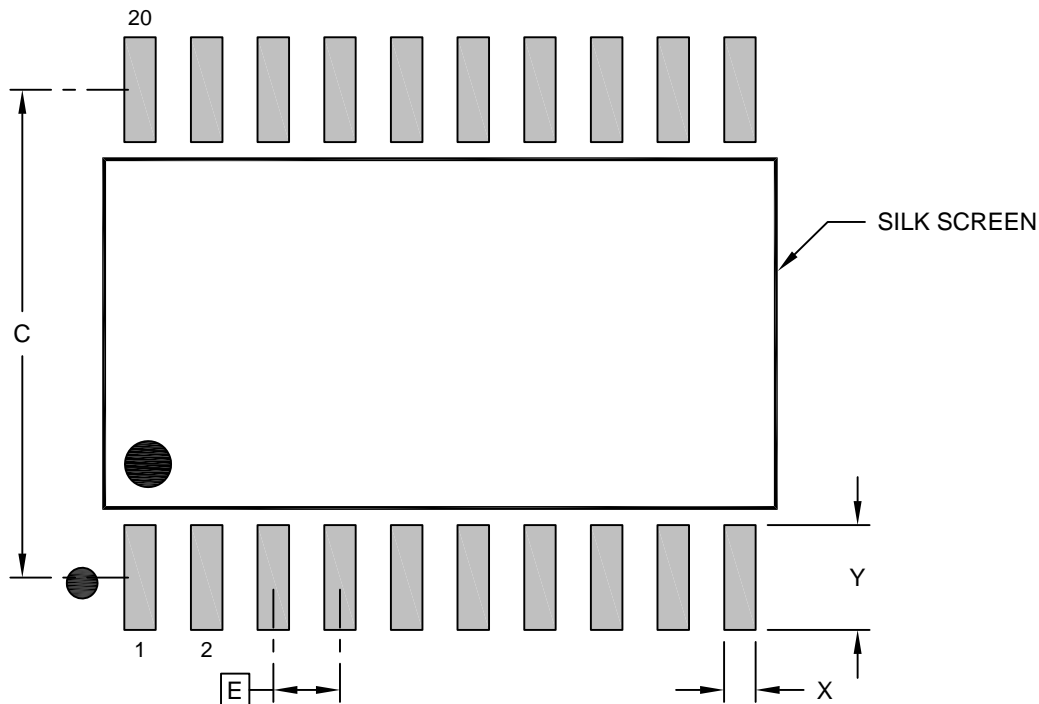


20-Lead Small Outline Integrated Circuit (MDB) - 7.50 mm (.300 In.) Body [SOIC]

Atmel Legacy Global Package Code SRJ

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		1.27		
Contact Pad Spacing	C			9.30	
Contact Pad Width (Xnn)	X				0.60
Contact Pad Length (Xnn)	Y				2.00

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process